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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/800,630	03/16/2004	Kazuhiro Tashiro	042236	9692

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EXAMINER

HUYNH, ANDY

ART UNIT PAPER NUMBER

2818

SHORTENED STATUTORY PERIOD OF RESPONSE	MAIL DATE	DELIVERY MODE
3 MONTHS	04/19/2007	PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

If NO period for reply is specified above, the maximum statutory period will apply and will expire 6 MONTHS from the mailing date of this communication.

DETAILED ACTION

This is responsive to Amendment filed February 02, 2007. By this Amendment, no claims have been amended. Claims **6 and 11** have been canceled. Claims **1-4, 21 and 22** have been withdrawn from consideration as being directed to a non-elected invention. Accordingly, claims **5, 7-10, 12-20 and 23-25** remain pending in this application.

Response to Arguments

Applicants' arguments filed February 02, 2007, have been fully considered but they are not persuasive.

In response to applicant's argument that reference numeral 2A is a housing of the socket but not the substrate of the semiconductor device. The term substrate of the semiconductor device is used to indicate the body of the semiconductor device 11 or interposer 13 in the specification and drawings, but the term is never used meaning a portion of a socket or anything else outside the semiconductor device. The examiner respectfully disagrees. The "a substrate of the semiconductor device" is a general or broad term it may be interpreted as a base of the semiconductor device, a printed circuit board of the semiconductor device, a wiring substrate of the semiconductor device, a mounting board of the semiconductor device, or a housing of a socket of the semiconductor device etc. For the above reasons, it is believed that the rejections should be sustained.

Claim Rejections - 35 U.S.C. § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 5, 9, 12-19, 24 and 25 are rejected under 35 U.S.C. 102(b) as being anticipated by JP 2001-015237.

Regarding Claim 5, JP 2001-015237 discloses in Figs. 2 and 8 a semiconductor device protection cover 2B attached to a semiconductor device 1, comprising:

- a base portion;
- a first surface, said first surface being flat (Fig. 8);
- a second surface having a projecting portion to be brought into contact with a substrate 2A of the semiconductor device and a depressed portion not to be brought into contact with parts mounted in the semiconductor device; and
- an engaging portion to engage the semiconductor device protection cover with the semiconductor device, so as to detachably attach the semiconductor device protection cover to the semiconductor device (see Fig. 2, English Abstract).

Regarding Claims 9 and 13, JP 2001-015237 discloses in Figs. 2 and 8 a semiconductor device protection cover 2B attached to a semiconductor device 1, comprising:

- a base portion;

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a first surface, said first surface being flat (Fig. 8); and

a second surface to be brought into contact with a substrate 2A of and parts mounted in the semiconductor device, said second surface being formed from an elastic material (par. [0009]),

wherein the semiconductor device protection cover has a structure to engage with the semiconductor device so as to be detachably attached to the semiconductor device (see Fig. 2, English Abstract).

Regarding Claims **12, 24 and 25**, JP 2001-015237 discloses in Fig. 2 the base portion has a predetermined shape irrespective of an outer shape of the semiconductor device; the depressed portion forming an opening penetrating through the base portion; and the depressed portion forming a plurality of openings penetrating through the base portion and a plurality of ribs between the openings.

Regarding Claim **14**, JP 2001-015237 discloses in Figs. 2 and 8 a semiconductor device unit, comprising:

a semiconductor device 1; and

a semiconductor device protection cover 2B,

wherein the semiconductor device protection cover comprises:

a base portion;

a first surface, said first surface being flat (Fig. 8); and

a second surface having a projecting portion to be brought into contact with a substrate 2A of the semiconductor device and a depressed portion not to be brought into contact with parts mounted in the semiconductor device,

wherein the semiconductor device protection cover has a structure to engage with the semiconductor device so as to be detachably attached to the semiconductor device (see Fig. 2, English Abstract).

Regarding Claims **15, 16 and 17**, JP 2001-015237 discloses in Fig. 2 the semiconductor device has a first positioning member; and the semiconductor device protection cover has a second positioning member, the semiconductor device and the semiconductor device protection cover being set in position when the first positioning member and the second positioning member are engaged with each other; the first positioning member is a projection; and the second positioning member is a recess engagable with the projection; wherein an inclined surface 2C is formed on the projection for guiding insertion of the projection into the recess.

Regarding Claims **18 and 19**, JP 2001-015237 discloses in Fig. 2 the first positioning member is a peripheral part of the semiconductor device; and the second positioning member is a wall engagable with the peripheral part; wherein an inclined surface 2C is formed on the second positioning member for guiding the first positioning member to engage with the second positioning member.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims **7, 8, 10 and 20** are rejected under 35 U.S.C. 103(a) as being unpatentable over JP 2001-015237.

JP 2001-015237 does not disclose the projecting portion and the base portion of the semiconductor device protection cover are formed from materials having hardness higher/lower than a surface of the semiconductor device; the projecting portion and the base portion of the semiconductor device protection cover have conductivity; the first positioning member and the second positioning member are formed by recognition marks. It would have been obvious to one having ordinary skill in the art at the time of the invention was made to form the projecting portion and the base portion of the semiconductor device protection cover from materials having hardness higher/lower than a surface of the semiconductor device, and the projecting portion and the base portion of the semiconductor device protection cover have conductivity, since it has been held to be within the general skill of a worker in the art to select a known material on the basis of its suitability for the intended use as a matter of obvious design choice. In re Leshin, 125 USPQ 416. Also, it would have been obvious to one having ordinary skill in the art at the time of the invention was made to form the first positioning member and the second positioning member by recognition marks in order to align the first positioning member and the second positioning member.

Allowable Subject Matter

Claim 23 is objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims, since the prior art made of record and considered pertinent to the applicant's disclosure does not teach or suggest the claimed limitations.

Conclusion

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Andy Huynh whose telephone number is (571) 272-1781. The examiner can normally be reached on Monday-Friday 6:30am-3:00pm. The fax phone numbers

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for the organization where this application or proceeding is assigned are (571) 273-8300 for regular communications and (703) 308-7722 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

Ah



Andy Huynh
Primary Examiner